

What is claimed is:

1. A semiconductor device package comprising a lead frame having a conductive pad section with first and second opposite surfaces and a plurality a coplanar pin sections, a first and at least a second semiconductor die, each having first and second opposite surfaces and each having a plurality of electrodes; said first electrodes of each of said first and second die being fixed to and in surface to surface connection with said first and second opposite surfaces respectively of said pad section; said first and second die being in spacial overlapping relationship with respect to one another; and an insulation housing enclosing said die and said pad section; said pin section extending through the surface of said insulation housing to its exterior.
2. The device of claim 1, wherein selected ones of said plurality of electrodes are connected to selected ones of said plurality of pins within said insulation housing.
3. The device of claim 1, which further includes a conductive adhesive for connecting said one surface of said first die to said first surface of said pad.
4. The device of claim 3, which further includes a second adhesive for connecting said one surface of said second die to said second surface of said pad.
5. The device of claim 4, wherein said second adhesive is electrically insulative.

6. The device of claim 3, wherein selected ones of said plurality of electrodes are connected to selected ones of said plurality of pins within said insulation housing

7. The device of claim 4, wherein selected ones of said plurality of electrodes are connected to selected ones of said plurality of pins within said insulation housing.

8. The device of claim 5, wherein selected ones of said plurality of electrodes are connected to selected ones of said plurality of pins within said insulation housing.

9. The package of claim 2, wherein said first and second die are MOSgated power devices; and wherein said first surfaces of said first and second die each contain a power electrode to be connected to said pad section and to one another.

10. The package of claim 9, wherein said first and second die are fixed to said pad section by a conductive adhesive.

11. The package of claim 2, wherein said first die is a MOSgated power device and said second die is a control IC coupled to selected electrodes of said first die.